1. A microcontroller, comprising:

a circuit comprising at least one of an analog circuit and a digital circuit;

a wirebond pad;

a processor;

a switching circuit that selectively connects the circuit to the wirebond pad under control of the processor.

2. The apparatus according to claim 1, wherein the analog circuit comprises a configurable analog circuit block.

3. The apparatus according to claim 1, wherein the digital circuit comprises a configurable digital circuit block.

4. The apparatus according to claim 1, wherein the analog circuit comprises an analog input and an analog output and wherein the switching circuit selectively connects one of the analog input and the analog output to the wirebond pad under control of the processor.

5. The apparatus according to claim 1, wherein the digital circuit comprises a digital input and a digital output and wherein the switching circuit selectively connects one of the digital input and the digital output to the wirebond pad under control of the processor.

6. The apparatus according to claim 1, wherein the analog circuit comprises an analog input and an analog output and wherein the digital circuit comprises a digital input and a digital output and wherein the switching circuit selectively connects at least one of the analog input, the analog output, the digital input and the digital output to the wirebond pad under control of the processor.

7. The apparatus according to claim 6, wherein the switching circuit comprises a tristate analog buffer amplifier coupling the analog output to the wirebond pad, and wherein the analog output is switched by tristate control of the tristate analog buffer amplifier.

8. The apparatus according to claim 6, wherein the switching circuit comprises an analog buffer amplifier in series with an analog switch coupling the analog output to the wirebond pad, and wherein the analog output is switched by the analog switch.

9. The apparatus according to claim 6, wherein the switching circuit comprises an analog switch coupling the analog output to the wirebond pad, and wherein the analog output is switched by the analog switch.

10. The apparatus according to claim 6, wherein the switching circuit comprises an analog switch coupling the analog input to the wirebond pad, and wherein the analog input is switched by the analog switch.

11. The apparatus according to claim 6, wherein the switching circuit comprises a tristate analog buffer amplifier coupling the analog input to the wirebond pad, and wherein the analog input is switched by tristate control of the tristate analog buffer amplifier.

12. The apparatus according to claim 6, wherein the switching circuit comprises a tristate logic gate coupling the digital output to the wirebond pad, and wherein the digital output is switched by tristate control of the tristate logic gate.

13. The apparatus according to claim 12, wherein the tristate logic gate comprises an inverter.

14. The apparatus according to claim 12, wherein the tristate logic gate comprises a buffer.

15. The apparatus according to claim 6, wherein the switching circuit comprises a multiple input logic gate coupling the digital output to the wirebond pad, and wherein the digital output is switched by an input to the multiple input logic gate.

16. The apparatus according to claim 15, wherein the multiple input logic gate comprises a NAND gate.

17. The apparatus according to claim 6, wherein the switching circuit comprises a tristate logic gate coupling the digital input to the wirebond pad, and wherein the digital input is switched by tristate control of the tristate logic gate.

18. The apparatus according to claim 17, wherein the tristate logic gate comprises an inverter.

19. The apparatus according to claim 17, wherein the tristate logic gate comprises a buffer.

20. The apparatus according to claim 6, wherein the switching circuit comprises a multiple input logic gate coupling the digital output to the wirebond pad, and wherein the digital input is switched by an input to the multiple input logic gate.

21. The apparatus according to claim 20, wherein the multiple input logic gate comprises a NAND gate.

22. The apparatus according to claim 6, wherein the switching circuit comprises an isolation resistor isolating the wirebond pad from one of a digital input, an analog input and analog output.